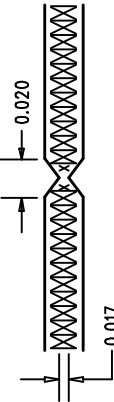


Component Side

SIZE	QTY	SYM	PLTD	TOL
10	555	+	YES	+/-3mil
95	3	X	YES	+/-3mil

Fabrication Drawing

11. SCORING:



UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ON ANGLE ± 1
3 PLACE ±.005
INTERPRET DIM AND TOL
PER ASME Y14.5M - 1994



1630 McCarthy Blvd.
Milpitas, CA 95035
PH: (408)432-1900

TITLE: LT5572EUF, I/Q Modulator w/Voltage
BB Interface 1.5-2.4GHz

SIZE	DEM	DC945A	REV.	A
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SHT 1 of 1

APPROVALS

DRAWN	INIT	DATE
CHECK		
DESIGN	Helen	06/24/05
ENGR	Doug S	06/24/05

SCALE = NONE

REVISIONS

REV	DESCRIPTION	APPR	DATE
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.062"	4 LAYERS	Microstrip
.018"		Core Material
.0014"		Microstrip
.0014"		Prepreg
.018"		Core Material
.0028"		Microstrip

NOTES : Unless Otherwise Specified

1. FAB PER IPC-A-600.
2. MATERIAL: EPOXY FIBERGLASS, NEMA GRADE FR-4.
2 OZ. COPPER FINISH ON OUTER LAYERS.
1 OZ. COPPER FINISH ON INNER LAYERS.
THICKNESS .062 +/- .006 TOTAL OF 4 LAYERS.
FLAMABILITY RATING: 94 V-0 MINIMUM .
3. SIZE: DIMENSIONS SHOWN AND TOLERANCES +/- .10MIL
0.00 ARE PRIMARY DATUMS.
4. DRILLING: DRILL HOLES PER SCHEDULE. PLATE THROUGH
HOLES WITH COPPER, .001 INCH THICK MIN. ALL
HOLE SIZES ARE SPECIFIED AFTER PLATING.
HOLE LOCATION TOLERANCES ARE +/- .3MIL
INCH IN RELATION TO CENTER
5. FINISH: SMOBC USING LPI BOTH SIDES COLOR GREEN.
WHITE TIN IMMERSION (OMIKRON) BOTH SIDES.
6. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK.
7. DO NOT ALTER ARTWORK e.g. TO ADD LOGO OR DATE CODE.
8. OUTER DIELECTRIC THICKNESS: TARGET 50-OHM USING 30MIL
TRACE CONTROLLED 50 OHM IMPEDANCE (AT 6GHz FREQ.) FOR
LAYER 1-2 . (TO BE FINALIZED BY MANUFACTURER)
(9) SUBJECT TO CHANGE BY MANUFACTURER, DEPENDING ON DIELECTRIC
CONSTANT DEVIATIONS. PLEASE CONSULT LTC.
10. INNER AND OUTER LAYER COPPER SHALL BE EXPOSED IN
TWO INSET AREAS ALONG BOARD EDGES.
DO NOT MODIFY INNER LAYER COPPER BACKOFF OUTLINE.